



SAW Components

Data Sheet R 711

Data Sheet

A decorative graphic at the bottom of the page, featuring a stylized globe with a grid of latitude and longitude lines, overlaid with a large, semi-transparent "EPCOS" logo. The globe is rendered in shades of gray and white, with a glowing effect around the edges.

OS



SAW Components	R 711
Resonator	392,85 MHz

Data Sheet

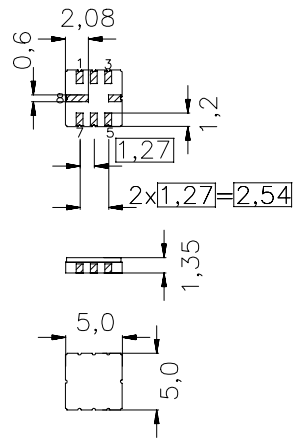
Features

- 1-port resonator
- Provides reliable, fundamental mode, quartz frequency stabilization i.e. in transmitters or local oscillators

Terminals

- Ni, gold plated

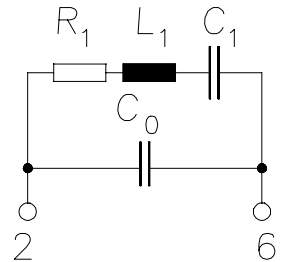
Ceramic package **QCC8C**



Dimensions in mm, approx. weight 0,1 g

Pin configuration

- | | |
|-----|---------------|
| 2 | Input |
| 6 | Ground |
| 4,8 | Ground (case) |



Type	Ordering code	Marking and Package according to	Packing according to
R 711	B39391-R 711-U310	C61157-A7-A56	F61074-V8070-Z000

Electrostatic Sensitive Device (ESD)



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Characteristics

Reference temperature: $T_A = 25\text{ °C}$
 Terminating source impedance: $Z_S = 50\ \Omega$
 Terminating load impedance: $Z_L = 50\ \Omega$

		min.	typ.	max.	
Center frequency ¹⁾	f_c	392,775	392,85	392,925	MHz
Minimum insertion attenuation	α_{\min}	—	1,4	1,9	dB
Unloaded quality factor	Q_U	8000	12000	—	
Ageing of f_c		—	—	± 50	ppm
Equivalent circuit elements					
Motional capacitance	C_1	—	2,31	—	fF
Motional inductance	L_1	—	71,05	—	μH
Motional resistance	R_1	—	16	25	Ω
Parallel capacitance	C_0	—	3,6	—	pF
Temperature coefficient of frequency ²⁾	TC_f	—	- 0,03	—	ppm/K ²
Turnover temperature	T_0	5	—	45	°C

1) Center frequency is defined as maximum of the real part of the admittance

2) Temperature dependence of f_c : $f_c(T_A) = f_c(T_0)(1 + TC_f(T_A - T_0)^2)$



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Resonator

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Published by EPCOS AG
Surface Acoustic Wave Components Division, OFW E UE
P.O. Box 80 17 09, D-81617 München

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